ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16693

Generic Copy

Issue Date: 25-Jul-2011

TITLE: Capacity expansion for SOIC-8 Products into STAR Microelectronics, Thailand

PROPOSED FIRST SHIP DATE: 25-Oct-2011

AFFECTED CHANGE CATEGORY(S): Subcontractor Assembly Site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Scott Brow <Scott.Brow@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or Scott Brow <Scott.Brow@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or <Ken.Fergus@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This notification is to announce ON Semiconductor is adding assembly manufacturing capacity for SOIC-8 products in STAR Microelectronics (Thailand) Public Company Limited. The change represents capacity expansion, and upon expiration of the PCN product may be sourced from STAR Microelectronics (Thailand) Public Company Limited or from any of the previously approved assembly suppliers.

SOIC-8 packages from STAR Microelectronics (Thailand) Public Company Limited are both Pb-Free & Halide Free

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test		Conditions	Results
HAST	Highly Accelerated Stress Test	Ta=130C, RH=85%, 18.8 psig, w/ bias; 96 HRS	0/240
PC-AC/UHAST	AC/Unbiased HAST Preconditioned	121C/100%RH, 15 psig; 96 HRS	0/240
PC-TC	Temperature Cycle Preconditioned	-65/+150C; 1000 cycles	0/240
HTSL	High Temperature Storage Life	Ta=150C; 1000 HRS	0/240
WBS	Wire Bond Shear		0/150 bonds
WBP	Wire Bond Pull		0/150 bonds

ELECTRICAL CHARACTERISTIC SUMMARY:

Product performance meets datasheet specifications.

CHANGED PART IDENTIFICATION:

Devices assembled by STAR Microelectronics will include the character ‘S’ as the identifier in the trace code. Upon expiration of the PCN devices may be sourced from either STAR Microelectronics, or previously qualified assembly locations. Manufacturing traceability will be maintained to allow identification of the assembly source.

As per JESD97, May 2004, section 5 the following information will be included to indicate the appropriate Pb-free 2nd level interconnect:

- Package labeling for material assembled in STARS will state ‘e4’, to indicate the use of precious metals, no Sn
- Package labeling for material assembled in previously qualified assembly locations will state ‘e3’ to indicate the use of Sn.

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List of affected General Parts:

PART
UC2842BD1G
UC2842BD1R2G
UC2843BD1G
UC2843BD1R2G
UC2844BD1R2G
UC2845BD1G
UC2845BD1R2G
UC3842BD1G
UC3842BD1R2G
UC3842BVD1G
UC3842BVD1R2G
UC3843BD1G
UC3843BD1R2G
UC3843BVD1G
UC3843BVD1R2G
UC3844BD1G
UC3844BD1R2G
UC3844BVD1G
UC3844BVD1R2G
UC3845BD1G
UC3845BD1R2G
UC3845BVD1G
UC3845BVD1R2G